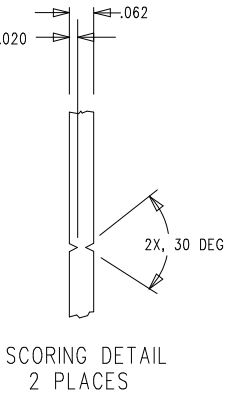
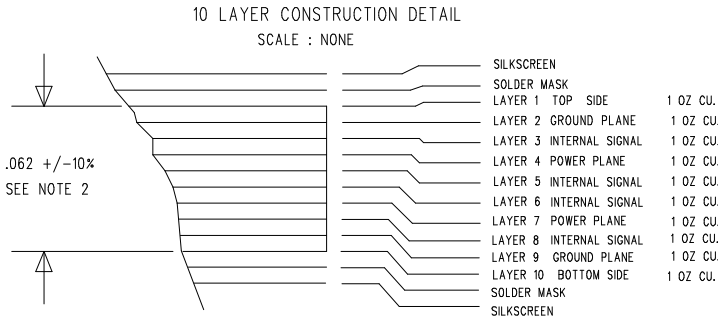
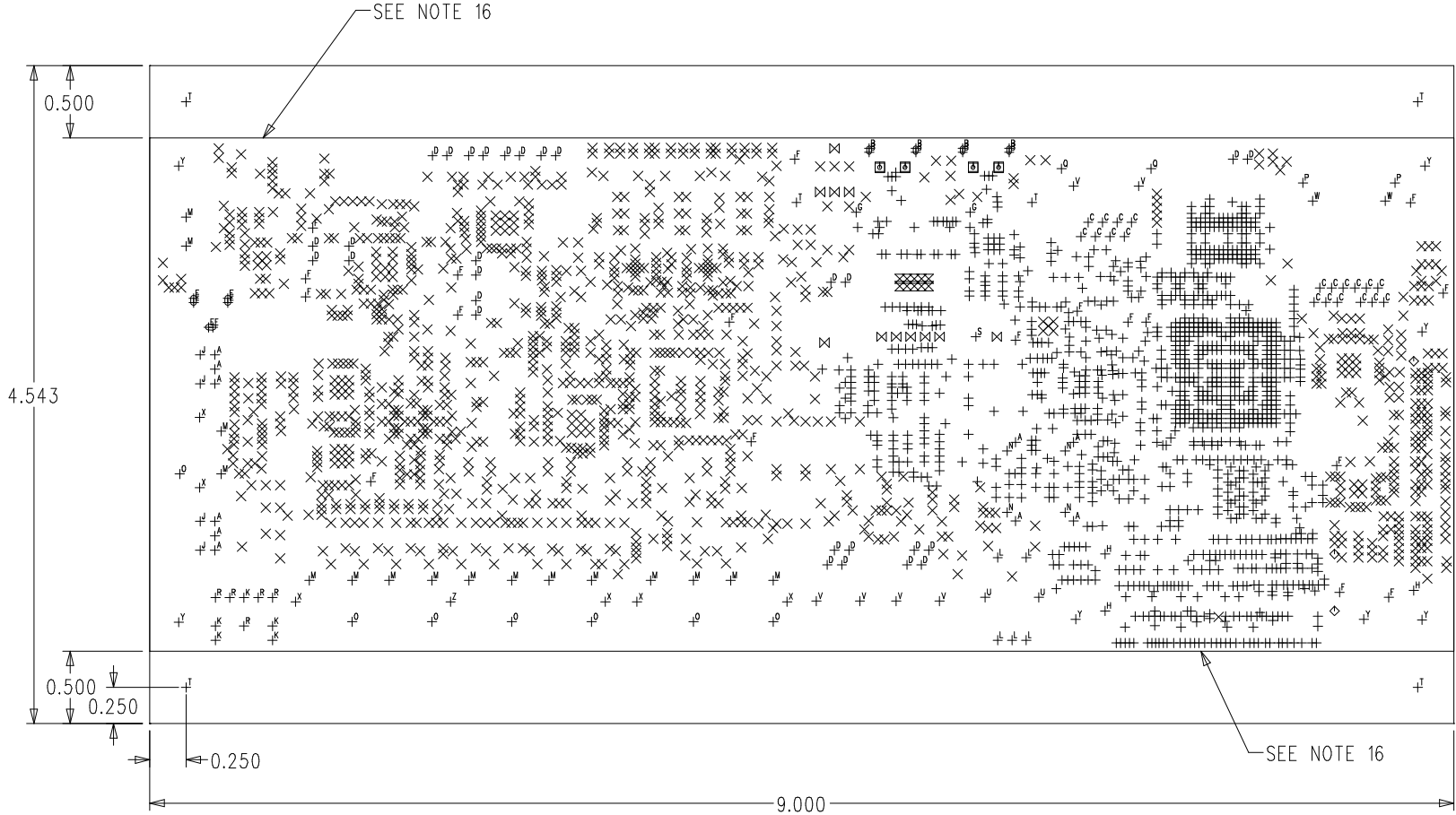



REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	08/20/14	
0.2	UPDATED PER ECO2014-086	C.C.D.	12/19/14	
1.0	UPDATED PER ECO2015-018	C.C.D.	05/12/15	
1.1	UPDATED PER ECO2016-014	C.C.D.	05/10/16	
1.2	UPDATED PER ECO2016-035	C.C.D.	08/05/16	
1.3	UPDATED PER ECO2017-012	C.C.D.	03/17/17	
1.4	UPDATED PER ECO2017-027	C.C.D.	10/24/17	

- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012B, CLASS 2.
 - MATERIAL: FR-370HR OR EQUIVALENT. OUTER LAYERS 1 OZ/SQFT CU INNER LAYERS 1 OZ/SQFT CU FINISHED .062 +/-10%. VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
 - PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE PER IPC-6012B WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
 - FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICROINCHES OVER A MINIMUM OF 150-200 MICROINCHES OF LOW STRESS NICKEL.
 - SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES. VENDOR MAY ADJUST SOLDERMASK PAD SIZE AS NEEDED.
 - SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
 - ARTWORK: MINIMUM FEATURE SIZE = 0.005
MINIMUM AIR GAP = 0.004
 - ALL DIMENSIONS ARE IN INCHES.
 - CONTROLLED IMPEDANCE (+/-10%):
ALL .005" TRACES TO BE 50 OHM SINGLE ENDED.
ALL .0056" TRACES TO BE 50 OHM SINGLE ENDED.
ALL .0045" TRACES TO BE 100 OHM DIFFERENTIAL PAIRS.
 - NON-FUNCTIONAL COPPER THIEVING IS ALLOWED ON OPEN AREAS.
 - VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1 IS PREFERRED.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
 - VIA HOLES (.006 & .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
 - TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
 - REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3, 5, 6, AND 8 IS ACCEPTABLE.
 - USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
 - V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
 - BUILD AS 1-UP PCB.

SIZE	QTY	SYM	PLATED	TOL
0.006	1367	+	YES	+0.000/-0.006
0.012	1386	×	YES	+/-0.003
0.026 x 0.033	4	□	YES	+/-0.003
0.028	3	◇	NO	+/-0.003
0.029	10	×	YES	+/-0.003
0.032	11	×	YES	+/-0.003
0.033	10	+	YES	+/-0.003
0.033 x 0.059	4	+	YES	+/-0.003
0.035	20	+	YES	+/-0.003
0.038	28	+	YES	+/-0.003
0.04	18	+	YES	+/-0.003
0.04	2	+	NO	+/-0.003
0.04 x 0.07	3	+	YES	+/-0.003
0.044	3	+	NO	+/-0.003
0.045	4	+	YES	+/-0.003
0.047	5	+	NO	+/-0.003
0.047	5	+	YES	+/-0.003
0.051	16	+	YES	+/-0.003
0.057	4	+	NO	+/-0.003
0.059	7	+	YES	+/-0.003
0.062	2	+	YES	+/-0.003
0.063	2	+	YES	+/-0.003
0.071	5	+	YES	+/-0.003
0.089	1	+	NO	+/-0.003
0.125	6	+	NO	+/-0.005
0.125	2	+	YES	+/-0.005
0.128	6	+	NO	+/-0.005
0.138	2	+	NO	+/-0.005
0.14	6	+	NO	+/-0.005
0.144	7	+	NO	+/-0.005
0.187	1	+	NO	+/-0.005



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .xx +/- .010 .xxx +/- .005	CONTRACT NO.		 2 Elizabeth Drive Chelmsford, MA 01824	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN CHECKED	C.C.D. 10/24/17	FABRICATION DRAWING ADSP-SC584 EZ-BOARD	
FINISH SEE NOTES	ENGINEERING QUALITY			
DO NOT SCALE THIS DRAWING	MANUFACTURING		SIZE B	REV. 1.4
		SCALE 1 : 1	DWG. NO. A0448-2013	SHEET 1 OF 1